NXP USA Inc. - MCHC908QY4MDWE Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.295", 7.50mm Width)
Supplier Device Package	16-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mchc908qy4mdwe

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List of Chapters

\$0000 ↓ \$003F	I/O REGISTERS 64 BYTES
\$0040 ↓ \$007F	RESERVED(1) 64 BYTES
\$0080 ↓ \$00FF	RAM 128 BYTES
\$0100 ↓ \$27FF	UNIMPLEMENTED(1) 9984 BYTES
\$2800 ↓ \$2DFF	AUXILIARY ROM 1536 BYTES
\$2E00 ↓ \$EDFF	UNIMPLEMENTED(1) 49152 BYTES
\$EE00 ↓ \$FDFF	FLASH MEMORY MC68HC908QT4 AND MC68HC908QY4 4096 BYTES
\$FE00	BREAK STATUS REGISTER (BSR)
\$FE01	RESET STATUS REGISTER (SRSR)
\$FE02	BREAK AUXILIARY REGISTER (BRKAR)
\$FE03	BREAK FLAG CONTROL REGISTER (BFCR)
\$FE04	INTERRUPT STATUS REGISTER 1 (INT1)
\$FE05	INTERRUPT STATUS REGISTER 2 (INT2)
\$FE06	INTERRUPT STATUS REGISTER 3 (INT3)
\$FE07	RESERVED FOR FLASH TEST CONTROL REGISTER (FLTCR)
\$FE08	FLASH CONTROL REGISTER (FLCR)
\$FE09	BREAK ADDRESS HIGH REGISTER (BRKH)
\$FE0A	BREAK ADDRESS LOW REGISTER (BRKL)
\$FE0B	BREAK STATUS AND CONTROL REGISTER (BRKSCR)
\$FE0C	LVISR
\$FE0D ↓ \$FE0F	RESERVED FOR FLASH TEST 3 BYTES
\$FE10 ↓ \$FFAF	MONITOR ROM 416 BYTES
\$FFB0 ↓ \$FFBD	FLASH 14 BYTES
\$FFBE	FLASH BLOCK PROTECT REGISTER (FLBPR)
\$FFBF	RESERVED FLASH
\$FFC0	INTERNAL OSCILLATOR TRIM VALUE (VDD = 5.0 V)
\$FFC1	INTERNAL OSCILLATOR TRIM VALUE (VDD = 3.0 V)
\$FFC2 ↓ \$FFCF	FLASH 14 BYTES
\$FFD0 ↓ \$FFFF	USER VECTORS 48 BYTES

Note 1.
Attempts to execute code from addresses in this range will generate an illegal address reset.

UNIMPLEMENTED 51712 BYTES	\$2E00 ↓ \$F7FF
FLASH MEMORY 1536 BYTES	\$F800 ↓ \$FDFF

MC68HC908QT1, MC68HC908QT2, MC68HC908QY1, and MC68HC908QY2 Memory Map

Figure 2-1. Memory Map

Table 2-1. Vector Addresses

Vector Priority	Vector	Address	Vector
Lowest ↑	IF15	$FFDE	ADC conversion complete vector (high)
		$FFDF	ADC conversion complete vector (low)
	IF14	$FFE0	Keyboard vector (high)
		$FFE1	Keyboard vector (low)
	IF13 ↓ IF6	—	Not used
	IF5	$FFF2	TIM overflow vector (high)
		$FFF3	TIM overflow vector (low)
	IF4	$FFF4	TIM Channel 1 vector (high)
		$FFF5	TIM Channel 1 vector (low)
	IF3	$FFF6	TIM Channel 0 vector (high)
		$FFF7	TIM Channel 0 vector (low)
	IF2	—	Not used
	IF1	$FFFA	$\overline{\text{IRQ}}$ vector (high)
		$FFFB	$\overline{\text{IRQ}}$ vector (low)
	—	$FFFC	SWI vector (high)
		$FFFD	SWI vector (low)
	—	$FFFE	Reset vector (high)
↓ Highest		$FFFF	Reset vector (low)

2.5 Random-Access Memory (RAM)

Addresses $0080–$00FF are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

NOTE

For correct operation, the stack pointer must point only to RAM locations.

Before processing an interrupt, the central processor unit (CPU) uses five bytes of the stack to save the contents of the CPU registers.

NOTE

For M6805, M146805, and M68HC05 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

Chapter 6
Computer Operating Properly (COP)

6.1 Introduction

The computer operating properly (COP) module contains a free-running counter that generates a reset if allowed to overflow. The COP module helps software recover from runaway code. Prevent a COP reset by clearing the COP counter periodically. The COP module can be disabled through the COPD bit in the configuration 1 (CONFIG1) register.

6.2 Functional Description

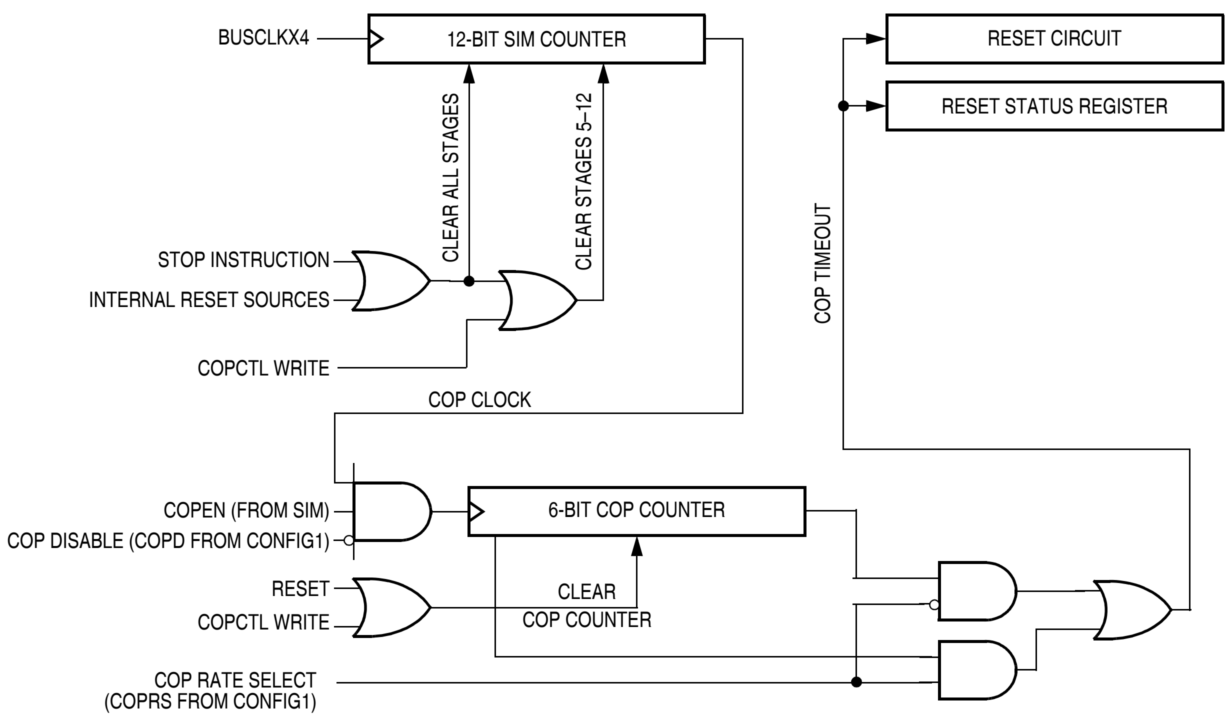


Figure 6-1. COP Block Diagram

Table 7-1. Instruction Set Summary (Sheet 5 of 6)

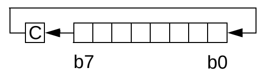
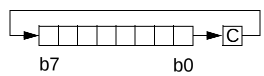
Source Form	Operation	Description	Effect on CCR V	H	I	N	Z	C	Address Mode	Opcode	Operand	Cycles
PULA	Pull A from Stack	SP ← (SP + 1); Pull (A)	–	–	–	–	–	–	INH	86		2
PULH	Pull H from Stack	SP ← (SP + 1); Pull (H)	–	–	–	–	–	–	INH	8A		2
PULX	Pull X from Stack	SP ← (SP + 1); Pull (X)	–	–	–	–	–	–	INH	88		2
ROL *opr* ROLA ROLX ROL *opr*,X ROL ,X ROL *opr*,SP	Rotate Left through Carry		↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	4 1 1 4 3 5
ROR *opr* RORA RORX ROR *opr*,X ROR ,X ROR *opr*,SP	Rotate Right through Carry		↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	4 1 1 4 3 5
RSP	Reset Stack Pointer	SP ← $FF	–	–	–	–	–	–	INH	9C		1
RTI	Return from Interrupt	SP ← (SP) + 1; Pull (CCR) SP ← (SP) + 1; Pull (A) SP ← (SP) + 1; Pull (X) SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL)	↕	↕	↕	↕	↕	↕	INH	80		7
RTS	Return from Subroutine	SP ← SP + 1; Pull (PCH) SP ← SP + 1; Pull (PCL)	–	–	–	–	–	–	INH	81		4
SBC #*opr* SBC *opr* SBC *opr* SBC *opr*,X SBC *opr*,X SBC ,X SBC *opr*,SP SBC *opr*,SP	Subtract with Carry	A ← (A) – (M) – (C)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A2 B2 C2 D2 E2 F2 9EE2 9ED2	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
SEC	Set Carry Bit	C ← 1	–	–	–	–	–	1	INH	99		1
SEI	Set Interrupt Mask	I ← 1	–	–	1	–	–	–	INH	9B		2
STA *opr* STA *opr* STA *opr*,X STA *opr*,X STA ,X STA *opr*,SP STA *opr*,SP	Store A in M	M ← (A)	0	–	–	↕	↕	–	DIR EXT IX2 IX1 IX SP1 SP2	B7 C7 D7 E7 F7 9EE7 9ED7	dd hh ll ee ff ff ff ee ff	3 4 4 3 2 4 5
STHX *opr*	Store H:X in M	(M:M + 1) ← (H:X)	0	–	–	↕	↕	–	DIR	35	dd	4
STOP	Enable Interrupts, Stop Processing, Refer to MCU Documentation	I ← 0; Stop Processing	–	–	0	–	–	–	INH	8E		1
STX *opr* STX *opr* STX *opr*,X STX *opr*,X STX ,X STX *opr*,SP STX *opr*,SP	Store X in M	M ← (X)	0	–	–	↕	↕	–	DIR EXT IX2 IX1 IX SP1 SP2	BF CF DF EF FF 9EEF 9EDF	dd hh ll ee ff ff ff ee ff	3 4 4 3 2 4 5
SUB #*opr* SUB *opr* SUB *opr* SUB *opr*,X SUB *opr*,X SUB ,X SUB *opr*,SP SUB *opr*,SP	Subtract	A ← (A) – (M)	↕	–	–	↕	↕	↕	IMM DIR EXT IX2 IX1 IX SP1 SP2	A0 B0 C0 D0 E0 F0 9EE0 9ED0	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5

Table 7-1. Instruction Set Summary (Sheet 6 of 6)

Source Form	Operation	Description	Effect on CCR V	H	I	N	Z	C	Address Mode	Opcode	Operand	Cycles
SWI	Software Interrupt	PC ← (PC) + 1; Push (PCL) SP ← (SP) – 1; Push (PCH) SP ← (SP) – 1; Push (X) SP ← (SP) – 1; Push (A) SP ← (SP) – 1; Push (CCR) SP ← (SP) – 1; I ← 1 PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	–	–	1	–	–	–	INH	83		9
TAP	Transfer A to CCR	CCR ← (A)	↕	↕	↕	↕	↕	↕	INH	84		2
TAX	Transfer A to X	X ← (A)	–	–	–	–	–	–	INH	97		1
TPA	Transfer CCR to A	A ← (CCR)	–	–	–	–	–	–	INH	85		1
TST *opr* TSTA TSTX TST *opr*,X TST ,X TST *opr*,SP	Test for Negative or Zero	(A) – \$00 or (X) – \$00 or (M) – \$00	0	–	–	↕	↕	–	DIR INH INH IX1 IX SP1	3D 4D 5D 6D 7D 9E6D	dd ff ff	3 1 1 3 2 4
TSX	Transfer SP to H:X	H:X ← (SP) + 1	–	–	–	–	–	–	INH	95		2
TXA	Transfer X to A	A ← (X)	–	–	–	–	–	–	INH	9F		1
TXS	Transfer H:X to SP	(SP) ← (H:X) – 1	–	–	–	–	–	–	INH	94		2
WAIT	Enable Interrupts; Wait for Interrupt	I bit ← 0; Inhibit CPU clocking until interrupted	–	–	0	–	–	–	INH	8F		1

A	Accumulator
C	Carry/borrow bit
CCR	Condition code register
dd	Direct address of operand
dd rr	Direct address of operand and relative offset of branch instruction
DD	Direct to direct addressing mode
DIR	Direct addressing mode
DIX+	Direct to indexed with post increment addressing mode
ee ff	High and low bytes of offset in indexed, 16-bit offset addressing
EXT	Extended addressing mode
ff	Offset byte in indexed, 8-bit offset addressing
H	Half-carry bit
H	Index register high byte
hh ll	High and low bytes of operand address in extended addressing
I	Interrupt mask
ii	Immediate operand byte
IMD	Immediate source to direct destination addressing mode
IMM	Immediate addressing mode
INH	Inherent addressing mode
IX	Indexed, no offset addressing mode
IX+	Indexed, no offset, post increment addressing mode
IX+D	Indexed with post increment to direct addressing mode
IX1	Indexed, 8-bit offset addressing mode
IX1+	Indexed, 8-bit offset, post increment addressing mode
IX2	Indexed, 16-bit offset addressing mode
M	Memory location
N	Negative bit
n	Any bit
opr	Operand (one or two bytes)
PC	Program counter
PCH	Program counter high byte
PCL	Program counter low byte
REL	Relative addressing mode
rel	Relative program counter offset byte
rr	Relative program counter offset byte
SP1	Stack pointer, 8-bit offset addressing mode
SP2	Stack pointer 16-bit offset addressing mode
SP	Stack pointer
U	Undefined
V	Overflow bit
X	Index register low byte
Z	Zero bit
&	Logical AND
|	Logical OR
⊕	Logical EXCLUSIVE OR
( )	Contents of
–( )	Negation (two's complement)
#	Immediate value
«	Sign extend
←	Loaded with
?	If
:	Concatenated with
↕	Set or cleared
—	Not affected

7.8 Opcode Map

See Table 7-2.

Chapter 9
Keyboard Interrupt Module (KBI)

9.1 Introduction

The keyboard interrupt module (KBI) provides six independently maskable external interrupts, which are accessible via the PTA0–PTA5 pins.

9.2 Features

Features of the keyboard interrupt module include:

- Six keyboard interrupt pins with separate keyboard interrupt enable bits and one keyboard interrupt mask
- Software configurable pullup device if input pin is configured as input port bit
- Programmable edge-only or edge and level interrupt sensitivity
- Exit from low-power modes

9.3 Functional Description

The keyboard interrupt module controls the enabling/disabling of interrupt functions on the six port A pins. These six pins can be enabled/disabled independently of each other. Refer to Figure 9-2.

9.3.1 Keyboard Operation

Writing to the KBIE0–KBIE5 bits in the keyboard interrupt enable register (KBIER) independently enables or disables each port A pin as a keyboard interrupt pin. Enabling a keyboard interrupt pin in port A also enables its internal pullup device irrespective of PTAPUEx bits in the port A input pullup enable register (see 12.2.3 Port A Input Pullup Enable Register). A logic 0 applied to an enabled keyboard interrupt pin latches a keyboard interrupt request.

A keyboard interrupt is latched when one or more keyboard interrupt inputs goes low after all were high. The MODEK bit in the keyboard status and control register controls the triggering mode of the keyboard interrupt.

- If the keyboard interrupt is edge-sensitive only, a falling edge on a keyboard interrupt input does not latch an interrupt request if another keyboard pin is already low. To prevent losing an interrupt request on one input because another input is still low, software can disable the latter input while it is low.
- If the keyboard interrupt is falling edge and low-level sensitive, an interrupt request is present as long as any keyboard interrupt input is low.

again in the SIM and results in the internal bus frequency being one fourth of either the XTALCLK, RCCLK, or INTCLK frequency.

11.5 Low Power Modes

The WAIT and STOP instructions put the MCU in low-power consumption standby modes.

11.5.1 Wait Mode

The WAIT instruction has no effect on the oscillator logic. BUSCLKX2 and BUSCLKX4 continue to drive to the SIM module.

11.5.2 Stop Mode

The STOP instruction disables either the XTALCLK, the RCCLK, or INTCLK output, hence BUSCLKX2 and BUSCLKX4.

11.6 Oscillator During Break Mode

The oscillator continues to drive BUSCLKX2 and BUSCLKX4 when the device enters the break state.

11.7 CONFIG2 Options

Two CONFIG2 register options affect the operation of the oscillator module: OSCOPT1 and OSCOPT0. All CONFIG2 register bits will have a default configuration. Refer to Chapter 5 Configuration Register (CONFIG) for more information on how the CONFIG2 register is used.

Table 11-2 shows how the OSCOPT bits are used to select the oscillator clock source.

Table 11-2. Oscillator Modes

OSCOPT1	OSCOPT0	Oscillator Modes
0	0	Internal oscillator
0	1	External oscillator
1	0	External RC
1	1	External crystal

11.8 Input/Output (I/O) Registers

The oscillator module contains these two registers:

1. Oscillator status register (OSCSTAT)
2. Oscillator trim register (OSCTRIM)

12.3.3 Port B Input Pullup Enable Register

The port B input pullup enable register (PTBPUE) contains a software configurable pullup device for each of the eight port B pins. Each bit is individually configurable and requires the corresponding data direction register, DDRBx, be configured as input. Each pullup device is automatically and dynamically disabled when its corresponding DDRBx bit is configured as output.

Address: $000C

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	PTBPUE7	PTBPUE6	PTBPUE5	PTBPUE4	PTBPUE3	PTBPUE2	PTBPUE2	PTBPUE0
Reset:	0	0	0	0	0	0	0	0

Figure 12-8. Port B Input Pullup Enable Register (PTBPUE)

PTBPUE[7:0] — Port B Input Pullup Enable Bits

These read/write bits are software programmable to enable pullup devices on port B pins

1 = Corresponding port B pin configured to have internal pull if its DDRB bit is set to 0

0 = Pullup device is disconnected on the corresponding port B pin regardless of the state of its DDRB bit.

Table 12-3 summarizes the operation of the port B pins.

Table 12-3. Port B Pin Functions

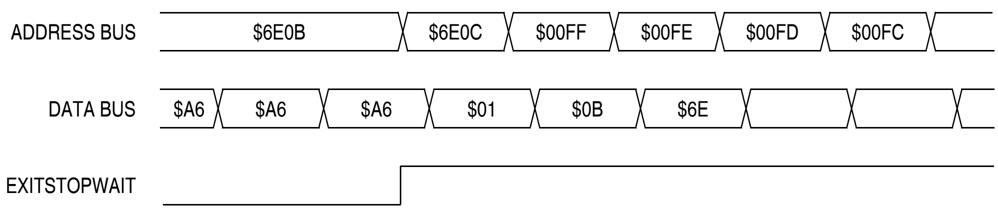
PTBPUE Bit	DDRB Bit	PTB Bit	I/O Pin Mode	Accesses to DDRB	Accesses to PTB	
				Read/Write	Read	Write
1	0	X(1)	Input, V_{DD}(2)	DDRB7–DDRB0	Pin	PTB7–PTB0(3)
0	0	X	Input, Hi-Z(4)	DDRB7–DDRB0	Pin	PTB7–PTB0(3)
X	1	X	Output	DDRB7–DDRB0	PTB7–PTB0	PTB7–PTB0

1. X = don't care
2. I/O pin pulled to V_{DD} by internal pullup.
3. Writing affects data register, but does not affect input.
4. Hi-Z = high impedance

A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred. In wait mode, the CPU clocks are inactive. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

Wait mode can also be exited by a reset (or break in emulation mode). A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the break status register (BSR). If the COP disable bit, COPD, in the configuration register is 0, then the computer operating properly module (COP) is enabled and remains active in wait mode.

Figure 13-15 and Figure 13-16 show the timing for wait recovery.



NOTE: EXITSTOPWAIT = $\overline{\text{RST}}$ pin OR CPU interrupt OR break interrupt

Figure 13-15. Wait Recovery from Interrupt

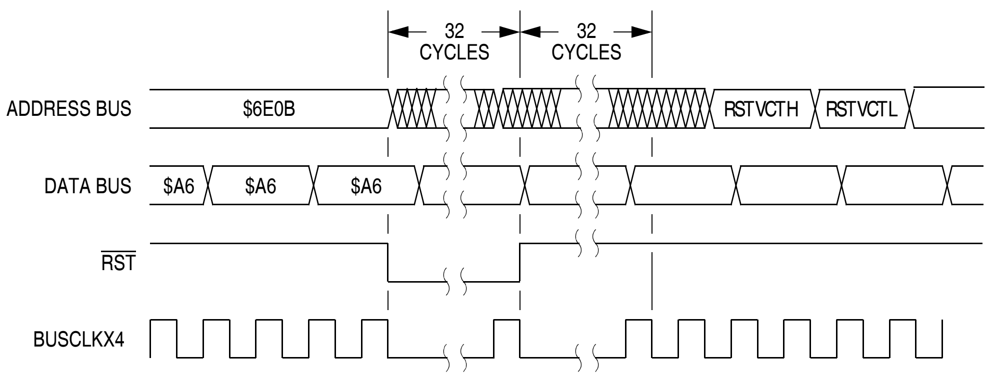


Figure 13-16. Wait Recovery from Internal Reset

13.7.2 Stop Mode

In stop mode, the SIM counter is reset and the system clocks are disabled. An interrupt request from a module can cause an exit from stop mode. Stacking for interrupts begins after the selected stop recovery time has elapsed. Reset or break also causes an exit from stop mode.

The SIM disables the oscillator signals (BUSCLKX2 and BUSCLKX4) in stop mode, stopping the CPU and peripherals. Stop recovery time is selectable using the SSREC bit in the configuration register 1 (CONFIG1). If SSREC is set, stop recovery is reduced from the normal delay of 4096 BUSCLKX4 cycles down to 32. This is ideal for the internal oscillator, RC oscillator, and external oscillator options which do not require long start-up times from stop mode.

NOTE

External crystal applications should use the full stop recovery time by clearing the SSREC bit.

CHxMAX — Channel x Maximum Duty Cycle Bit

When the TOVx bit is at a 1, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100%. As Figure 14-8 shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at the 100% duty cycle level until the cycle after CHxMAX is cleared.

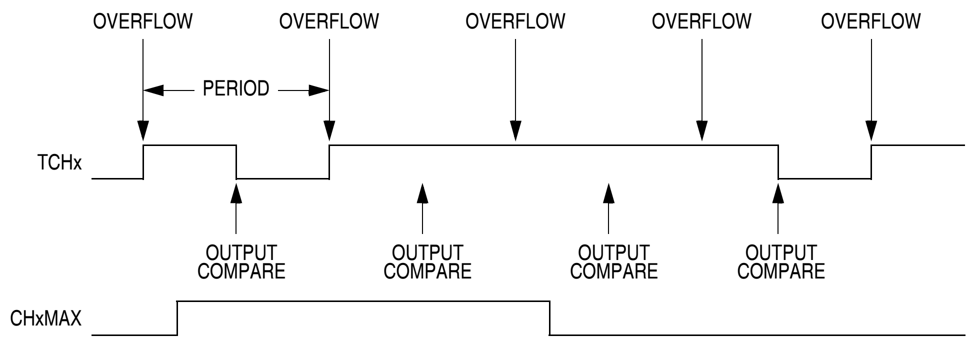


Figure 14-8. CHxMAX Latency

14.9.5 TIM Channel Registers

These read/write registers contain the captured TIM counter value of the input capture function or the output compare value of the output compare function. The state of the TIM channel registers after reset is unknown.

In input capture mode (MSxB:MSxA = 0:0), reading the high byte of the TIM channel x registers (TCHxH) inhibits input captures until the low byte (TCHxL) is read.

In output compare mode (MSxB:MSxA $\neq$ 0:0), writing to the high byte of the TIM channel x registers (TCHxH) inhibits output compares until the low byte (TCHxL) is written.

Address: $0026 TCH0H

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
Reset:	Indeterminate after reset							

Address: $0027 TCH0L

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reset:	Indeterminate after reset							

Address: $0029 TCH1H

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
Reset:	Indeterminate after reset							

Address: $02A TCH1L

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reset:	Indeterminate after reset							

Figure 14-9. TIM Channel Registers (TCH0H/L:TCH1H/L)

Table 15-1. Monitor Mode Signal Requirements and Options

Mode	$\overline{\text{IRQ}}$ (PTA2)	$\overline{\text{RST}}$ (PTA3)	Reset Vector	Serial Communi-cation	Mode Selection		COP	Communication Speed			Comments
				PTA0	PTA1	PTA4		External Clock	Bus Frequency	Baud Rate	
Normal Monitor	V_{TST}	V_{DD}	X	1	1	0	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.
Forced Monitor	V_{DD}	X	$FFFF (blank)	1	X	X	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.
	V_{SS}	X	$FFFF (blank)	1	X	X	Disabled	X	3.2 MHz (Trimmed)	9600	Internal clock is active.
User	X	X	Not $FFFF	X	X	X	Enabled	X	X	X	
MON08 Function [Pin No.]	V_{TST} [6]	$\overline{\text{RST}}$ [4]	—	COM [8]	MOD0 [12]	MOD1 [10]	—	OSC1 [13]	—	—	

1. PTA0 must have a pullup resistor to V_{DD} in monitor mode.
2. Communication speed in the table is an example to obtain a baud rate of 9600. Baud rate using external oscillator is bus frequency / 256 and baud rate using internal oscillator is bus frequency / 335.
3. External clock is a 9.8304 MHz oscillator on OSC1.
4. X = don't care
5. MON08 pin refers to P&E Microcomputer Systems' MON08-Cyclone 2 by 8-pin connector.

NC	1	2	GND
NC	3	4	$\overline{\text{RST}}$
NC	5	6	$\overline{\text{IRQ}}$
NC	7	8	PTA0
NC	9	10	PTA4
NC	11	12	PTA1
OSC1	13	14	NC
V_{DD}	15	16	NC

The rising edge of the internal $\overline{\text{RST}}$ signal latches the monitor mode. Once monitor mode is latched, the values on PTA1 and PTA4 pins can be changed.

Once out of reset, the MCU waits for the host to send eight security bytes (see 15.3.2 Security). After the security bytes, the MCU sends a break signal (10 consecutive logic 0s) to the host, indicating that it is ready to receive a command.

15.3.1.1 Normal Monitor Mode

$\overline{\text{RST}}$ and OSC1 functions will be active on the PTA3 and PTA5 pins respectively as long as V_{TST} is applied to the $\overline{\text{IRQ}}$ pin. If the $\overline{\text{IRQ}}$ pin is lowered (no longer V_{TST}) then the chip will still be operating in monitor mode, but the pin functions will be determined by the settings in the configuration registers (see Chapter 5 Configuration Register (CONFIG)) when V_{TST} was lowered. With V_{TST} lowered, the BIH and BIL instructions will read the $\overline{\text{IRQ}}$ pin state only if IRQEN is set in the CONFIG2 register.

Table 15-2. Mode Difference

Modes	Functions					
	Reset Vector High	Reset Vector Low	Break Vector High	Break Vector Low	SWI Vector High	SWI Vector Low
User	$FFFE	$FFFF	$FFFC	$FFFD	$FFFC	$FFFD
Monitor	$FEFE	$FEFF	$FEFC	$FEFD	$FEFC	$FEFD

15.3.1.4 Data Format

Communication with the monitor ROM is in standard non-return-to-zero (NRZ) mark/space data format. Transmit and receive baud rates must be identical.

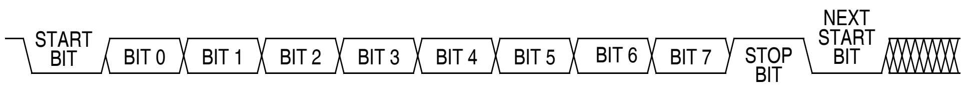


Figure 15-13. Monitor Data Format

15.3.1.5 Break Signal

A start bit (logic 0) followed by nine logic 0 bits is a break signal. When the monitor receives a break signal, it drives the PTA0 pin high for the duration of two bits and then echoes back the break signal.

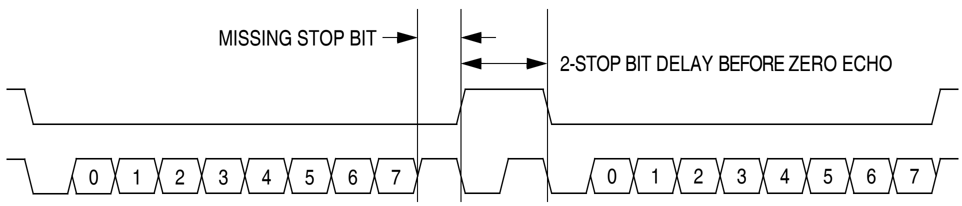


Figure 15-14. Break Transaction

15.3.1.6 Baud Rate

The monitor communication baud rate is controlled by the frequency of the external or internal oscillator and the state of the appropriate pins as shown in Table 15-1.

Table 15-1 also lists the bus frequencies to achieve standard baud rates. The effective baud rate is the bus frequency divided by 256 when using an external oscillator. When using the internal oscillator in forced monitor mode, the effective baud rate is the bus frequency divided by 335.

15.3.1.7 Commands

The monitor ROM firmware uses these commands:

- READ (read memory)
- WRITE (write memory)
- IREAD (indexed read)
- IWRITE (indexed write)
- READSP (read stack pointer)
- RUN (run user program)

Table 15-7. READSP (Read Stack Pointer) Command

Description	Reads stack pointer
Operand	None
Data Returned	Returns incremented stack pointer value (SP + 1) in high-byte:low-byte order
Opcode	$0C
Command Sequence	

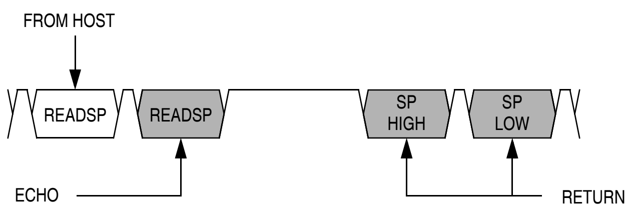
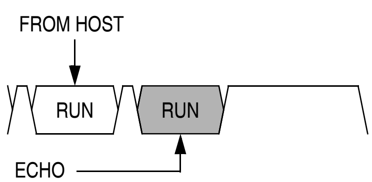


Table 15-8. RUN (Run User Program) Command

Description	Executes PULH and RTI instructions
Operand	None
Data Returned	None
Opcode	$28
Command Sequence	



The MCU executes the SWI and PSHH instructions when it enters monitor mode. The RUN command tells the MCU to execute the PULH and RTI instructions. Before sending the RUN command, the host can modify the stacked CPU registers to prepare to run the host program. The READSP command returns the incremented stack pointer value, SP + 1. The high and low bytes of the program counter are at addresses SP + 5 and SP + 6.

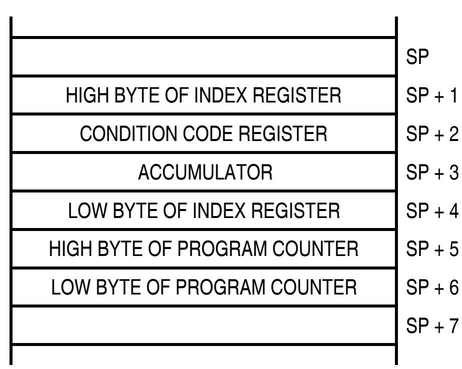


Figure 15-17. Stack Pointer at Monitor Mode Entry

15.3.2 Security

A security feature discourages unauthorized reading of FLASH locations while in monitor mode. The host can bypass the security feature at monitor mode entry by sending eight security bytes that match the bytes at locations $FFF6–$FFFD. Locations $FFF6–$FFFD contain user-defined data.

NOTE

Do not leave locations $FFF6–$FFFD blank. For security reasons, program locations $FFF6–$FFFD even if they are not used for vectors.

During monitor mode entry, the MCU waits after the power-on reset for the host to send the eight security bytes on pin PTA0. If the received bytes match those at locations $FFF6–$FFFD, the host bypasses the security feature and can read all FLASH locations and execute code from FLASH. Security remains bypassed until a power-on reset occurs. If the reset was not a power-on reset, security remains bypassed and security code entry is not required. See Figure 15-18.

Upon power-on reset, if the received bytes of the security code do not match the data at locations $FFF6–$FFFD, the host fails to bypass the security feature. The MCU remains in monitor mode, but reading a FLASH location returns an invalid value and trying to execute code from FLASH causes an illegal address reset. After receiving the eight security bytes from the host, the MCU transmits a break character, signifying that it is ready to receive a command.

NOTE

The MCU does not transmit a break character until after the host sends the eight security bytes.

To determine whether the security code entered is correct, check to see if bit 6 of RAM address $80 is set. If it is, then the correct security code has been entered and FLASH can be accessed.

If the security sequence fails, the device should be reset by a power-on reset and brought up in monitor mode to attempt another entry. After failing the security sequence, the FLASH module can also be mass erased by executing an erase routine that was downloaded into internal RAM. The mass erase operation clears the security code locations so that all eight security bytes become $FF (blank).

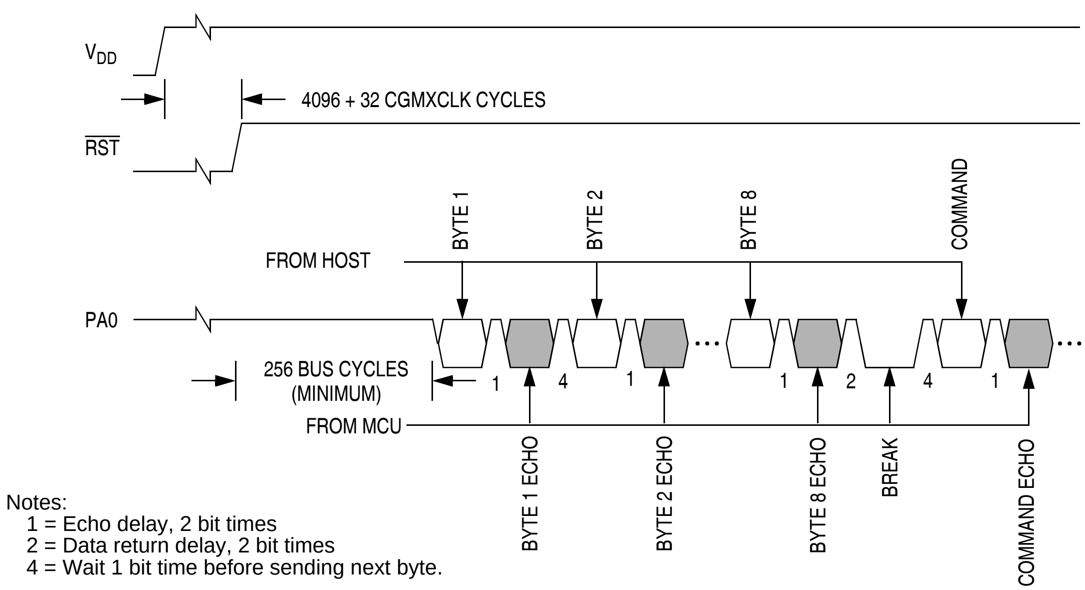


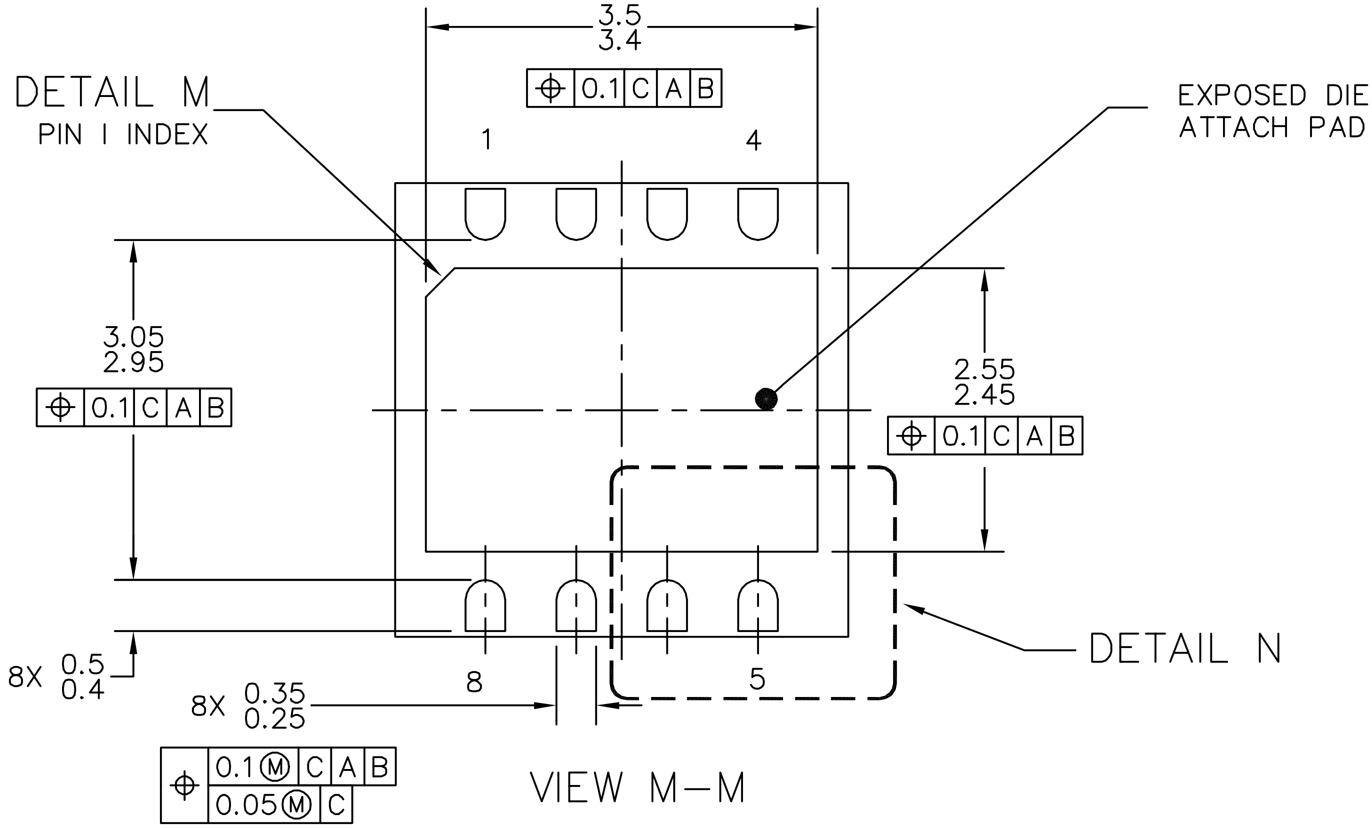
Figure 15-18. Monitor Mode Entry Timing

16.5 5-V DC Electrical Characteristics

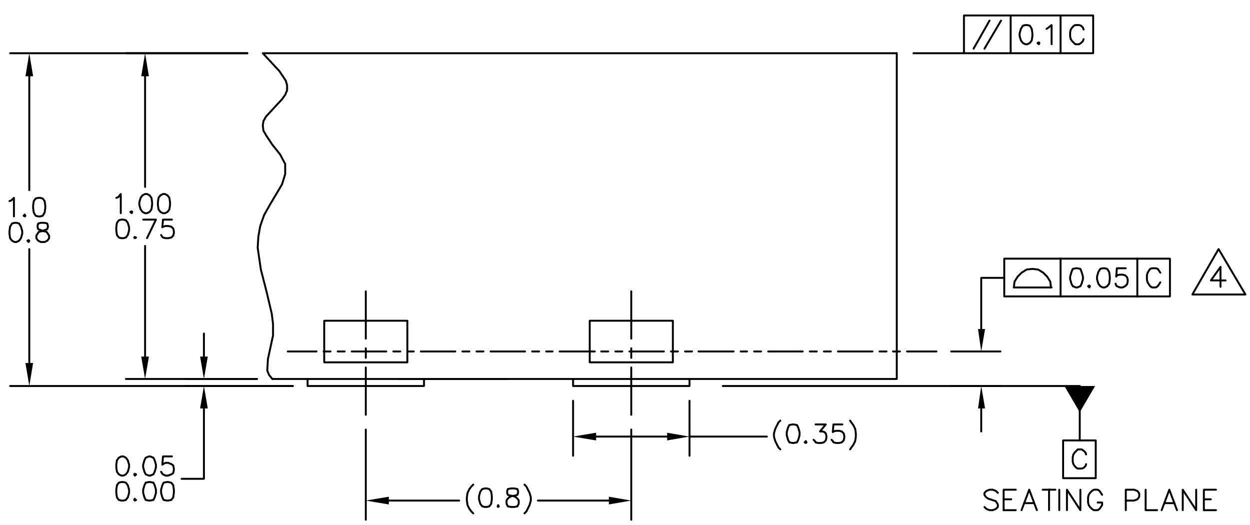
Characteristic[1]	Symbol	Min	Typ[2]	Max	Unit
Output high voltage I_{Load} = –2.0 mA, all I/O pins I_{Load} = –10.0 mA, all I/O pins I_{Load} = –15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OH}	V_{DD}–0.4 V_{DD}–1.5 V_{DD}–0.8	— — —	— — —	V
Maximum combined I_{OH} (all I/O pins)	I_{OHT}	—	—	50	mA
Output low voltage I_{Load} = 1.6 mA, all I/O pins I_{Load} = 10.0 mA, all I/O pins I_{Load} = 15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OL}	— — —	— — —	0.4 1.5 0.8	V
Maximum combined I_{OL} (all I/O pins)	I_{OLT}	—	—	50	mA
Input high voltage PTA0–PTA5, PTB0–PTB7	V_{IH}	0.7 x V_{DD}	—	V_{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V_{IL}	V_{SS}	—	0.3 x V_{DD}	V
Input hysteresis	V_{HYS}	0.06 x V_{DD}	—	—	V
DC injection current, all ports	I_{INJ}	–2	—	+2	mA
Total dc current injection (sum of all I/O)	I_{INJTOT}	–25	—	+25	mA
Ports Hi-Z leakage current	I_{IL}	–1	±0.1	+1	μA
Capacitance Ports (as input) Ports (as input)	C_{IN} C_{OUT}	— —	— —	12 8	pF
POR rearm voltage[3]	V_{POR}	0	—	100	mV
POR rise time ramp rate[4]	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage	V_{TST}	V_{DD} + 2.5	—	9.1	V
Pullup resistors[5] PTA0–PTA5, PTB0–PTB7	R_{PU}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V_{TRIPF}	3.90	4.20	4.50	V
Low-voltage inhibit reset, trip rising voltage	V_{TRIPR}	4.00	4.30	4.60	V
Low-voltage inhibit reset/recover hysteresis	V_{HYS}	—	100	—	mV

1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, $T_A = T_L$ to T_H, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.
3. Maximum is highest voltage that POR is guaranteed.
4. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
5. R_{PU} is measured at V_{DD} = 5.0 V.

MECHANICAL OUTLINES DICTIONARY	DOCUMENT NO: 98ARL10557D	
	PAGE:	1452
DO NOT SCALE THIS DRAWING	REV:	A



VIEW M–M



DETAIL G

TITLE: THERMALLY ENHANCED DUAL FLAT NO LEAD PACKAGE (DFN) 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)	CASE NUMBER: 1452–01	
	STANDARD: NON–JEDEC	
	PACKAGE CODE: 6165	SHEET: 2 OF 5

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. DATUMS A AND B TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.

4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.

5. THIS DIMENSION DOES NOT INCLUDE INTER–LEAD FLASH OR PROTRUSIONS. INTER–LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.

6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.62 mm.